Ultra High Performance BGA Cooling Solutions w/ maxiGRIP[™] Attachment*

DIGI-KEY PART # ATS1053-ND

ATS PART # ATS-51270D-C2-R0

Features & Benefits

maxiFLOW[™] design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling

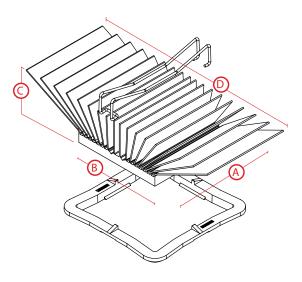
maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB

Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards

Comes preassembled with high performance, phase changing, thermal interface material

Thermal Performance Table

Designed for low profile components from 1.5 to 2.99mm





ADVANCED THERMAL

Innovations in Thermal Management®

SOLUTIONS, INC.

AIR VELOCITY THERMAL RESISTANCE °C/W (DUCTED) FT/MIN M/S °C/W (UNDUCTED) 8 200 1.0 5.3 300 1.5 6.3 5.4 400 2.0 4.9 500 2.5 4.4 600 3.0 700 3.5 4.1 800 4.0 3.9

Product Details[†]

DIMENSION A	DIMENSION B	DIMENSION C [§]	DIMENSION D	TIM [‡]	FINISH
27	27	9.5	43.2	C1100F	BLACK- ANODIZED

For further technical information, please contact Advanced Thermal Solutions, Inc. at 1-781-769-2800 or www.qats.com

* RoHS Compliant

± TIM = Thermal Interface Material

† Dimensions are measured in millimeters

Dimensions A & B refer to component size

§ Dimension C = the height of the heat sink shown above and does not include the height of the attachment method



To place an order, please visit www.digikey.com